

SBR1045CTL SBR1045D1 SBR10U45D1 SBR6100CTL

Part Number: **SBR DPAK**
Weight (mg): 317.9545

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Si, Doped	7440-21-3	100.00%	0.98	3.1117	1000000	9787
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.80	2.5361	925000	7378
		Sn	7440-31-5	5.00%			50000	399
		Ag	7440-22-4	2.50%			25000	199
Leadframe & Clip	Copper Alloy	Cu	7440-50-8	99.88%	52.81	167.8968	998800	527419
		Sn	7440-31-5	0.12%			1200	634
	Die pad plating	Ni	7440-02-0	100.00%	0.42	1.3219	1000000	4158
Encapsulation	Epoxy	Epoxy Resin	-----	7.50%	43.35	137.848	75000	32516
		Phenol Resin	-----	5.00%			50000	21677
		Bismuth/Bismuth compound	-----	0.05%			500	217
		SiO2	60676-86-0	86.95%			869500	376969
		C	1333-86-4	0.50%			5000	2168
Bonding Wire	15 mil Wire	Al	7429-90-5	100.00%	0.46	1.4534	1000000	4571
Lead Plating Finish	Tin Solder	Sn (>99.5%)	7440-31-5	100.00%	1.19	3.7866	5000	11909
Total						100.00	317.95	1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)

REACH SVHCs:

Anthracene	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
4,4'- Diaminodiphenylmethane	Bis (2-ethyl(hexyl)phthalate) (DEHP)
Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentaoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder applied